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(54) **Silicone pressure-sensitive adhesive composition and pressure-sensitive adhesive tape**

(57) A pressure-sensitive adhesive tape having a cured layer of a silicone pressure-sensitive adhesive composition containing a phenolic antioxidant is attached to an adherend of metal, typically copper for bonding or masking purposes. Even after exposure to

elevated temperatures of 150-250°C, the tape can be smoothly peeled from the adherend without leaving any adhesive residue.

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Description

[0001] This invention relates to a silicone pressure-sensitive adhesive composition and a pressure-sensitive adhesive tape which when is effectively attached to metals such as copper and leaves no adhesive residues after peeling off.

BACKGROUND

[0002] Pressure-sensitive adhesive tapes and labels using silicone pressure-sensitive adhesive compositions are utilized under rigorous environments where conventional pressure-sensitive adhesive compositions such as acrylic, rubber, urethane and epoxy base compositions can be altered or degraded. This is because silicone pressure-sensitive adhesive composition layers have excellent heat resistance, freeze resistance, weather resistance, electrical insulation and chemical resistance.

[0003] Such pressure-sensitive adhesive tapes are generally prepared by applying silicone pressure-sensitive adhesive compositions to plastic films or suitable supports and effecting crosslinking reaction to cure the compositions for improving tackiness.

[0004] Typical forms of pressure-sensitive adhesive tape include heat resistant pressure-sensitive adhesive tape and heat resistant masking tape in which pressure-sensitive adhesive compositions are applied to heat resistant supports, and chemical resistant masking tape.

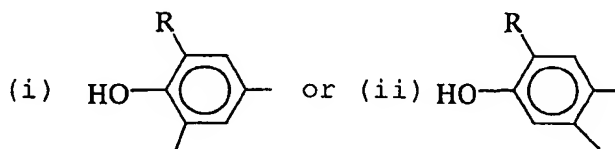
[0005] In the manufacture of printed circuit boards, the heat resistant masking tape and chemical resistant masking tape are used during etching, plating and soldering steps for preventing the processing solution (e.g., etching solution, plating solution) and solder from contacting unnecessary areas of electronic parts. While it should be avoided that when the adhesive tape is contacted with or immersed in the processing fluid or held under processing temperature conditions, the adhesive tape peels off or partially separates away allowing the area to be protected to be contaminated, it is also required that at the end of processing, the adhesive tape be smoothly peeled from the part without allowing residues of the adhesive to transfer to or remain on the part. If the adhesive transfers to or remains on the part, it can cause troubles in the ensuing manufacture of printed circuit boards.

[0006] The above-mentioned tape is also used during the manufacture of semiconductor devices for protecting lead frames or securing lead pins of lead frames. Even when the tape is exposed to elevated temperatures of 150 to 250°C in the steps of securing and bonding, wire bonding, and resin encapsulating of semiconductor chips, the adhesive layer should not peel off or partially separate away. Once the operation is completed, the tape must be peeled without allowing the adhesive to transfer to or remain on the adherend.

[0007] Regrettably, if a conventional pressure-sensitive adhesive tape using silicone adhesive is exposed to elevated temperatures of 150 to 250°C after attachment to a metal portion, especially of copper, copper alloy or iron, for bonding or masking purposes, the pressure-sensitive adhesive layer undergoes cohesive failure upon removal of the pressure-sensitive adhesive tape by peeling. Then some adhesive is left on the metal portion, or the adhesive layer transfers from the tape support to the metal portion. This is generally referred to as adhesive residue.

[0008] The aim herein is to provide new and useful pressure-sensitive silicone adhesives (and corresponding tapes/films) with a lesser tendency to leave adhesive residues. A preferred aim is a composition which even after exposure to elevated temperatures of 150 to 250°C during attachment to metal adherends such as copper, copper alloys and iron for bonding or masking purposes, can be smoothly peeled from the adherend without leaving any adhesive residue.

[0009] We have found that when a phenolic antioxidant is contained in a silicone pressure-sensitive adhesive composition, especially when a phenolic antioxidant is contained in a silicone pressure-sensitive adhesive composition of the addition reaction curing type, e.g. with a linear polydiorganosiloxane in which vinyl-bearing backbone is composed of R^1_2SiO units, a polyorganosiloxane of three-dimensional structure composed of $R^1_3SiO_{0.5}$ units and SiO_2 units, and a polyorganohydrosiloxane or platinum compound as a curing catalyst, e.g. as in JP-B 54-37907, one can obtain a silicone pressure-sensitive adhesive composition which is effectively attached to metals such as copper and does leave no adhesive residue after removal from the metal. The preferred phenolic antioxidant is a phenolic compound having in a molecule a structure of the following formula:



wherein R is a monovalent hydrocarbon group having 1 to 6 carbon atoms, preferably tert-butyl. The use of such a phenolic antioxidant enhances the effect especially when the pressure-sensitive adhesive is attached to a copper board or copper wiring, heat aged at 150 to 250°C, and thereafter, peeled therefrom, i.e. adhesive residue on the copper can be avoided. The 'open' bonds may preferably connect e.g. to moieties selected from other R groups (the same or different) and groups comprising one or more further phenolic groups, preferably of structure (i) or (ii) above, or to other moieties, but this is not critical: phenolic antioxidants are well known per se. Group A (defined below) is one preferred structure for (i).

[0010] So, one aspect herein is a silicone pressure-sensitive adhesive composition comprising a phenolic antioxidant.

[0011] In one preferred embodiment, a silicone pressure-sensitive adhesive composition comprising the following components (A) to (F) is provided.

(A) 20 to 80 parts by weight of an alkenyl group-containing polydiorganosiloxane,

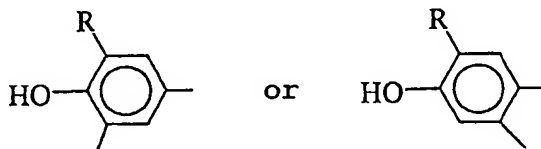
(B) 80 to 20 parts by weight of a polyorganosiloxane containing $R^1_3SiO_{0.5}$ units and SiO_2 units in a molar ratio between 0.6 and 1.7 wherein R^1 is a monovalent hydrocarbon group having 1 to 10 carbon atoms,

(C) a SiH group-containing polyorganosiloxane in an amount to provide 0.5 to 20 mol of SiH groups per mol of alkenyl groups in component (A),

(D) 0 to 5.0 parts by weight per 100 parts by weight of components (A) and (B) combined of a retarder,

(E) a platinum catalyst in an amount to give 1 to 5,000 ppm of platinum based on the weight of components (A) and (B) combined, and

(F) 0.1 to 10 parts by weight per 100 parts by weight of components (A) and (B) combined of a phenolic antioxidant in the form of a phenolic compound having in a molecule a structure of the following formula:



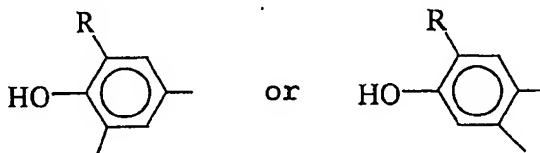
wherein R is a monovalent hydrocarbon group having 1 to 6 carbon atoms, typically tert-butyl.

[0012] Also contemplated herein is a pressure-sensitive adhesive tape comprising a cured layer of the silicone pressure-sensitive adhesive composition lying on at least one surface of plastic film.

[0013] The silicone pressure-sensitive adhesive composition and tape are useful as masking tape intended for electrical and electronic parts comprising copper or copper alloy.

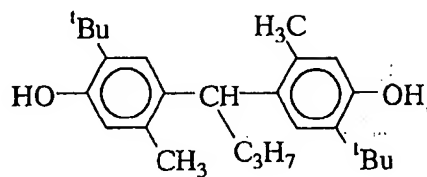
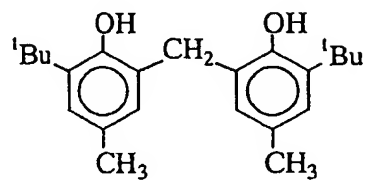
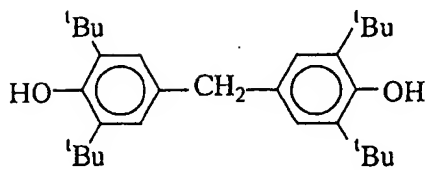
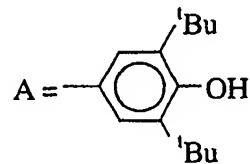
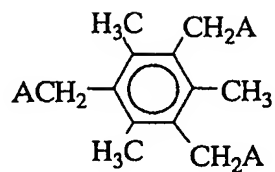
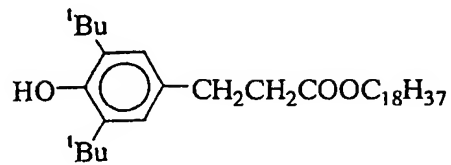
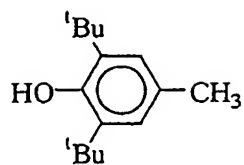
FURTHER EXPLANATIONS; OPTIONS AND PREFERRED FEATURES

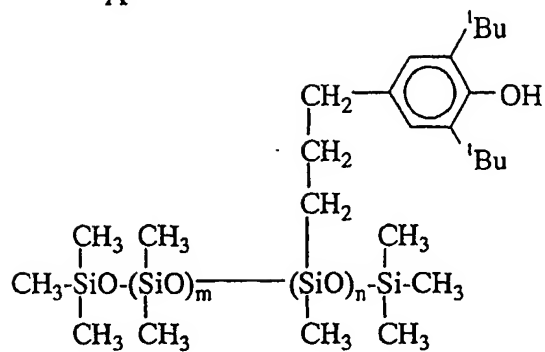
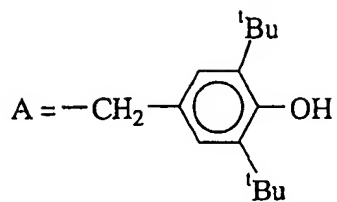
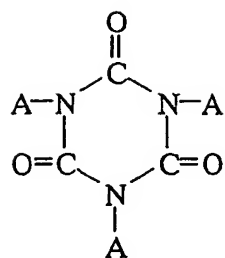
[0014] According to the present invention, a silicone pressure-sensitive adhesive composition comprising a phenolic antioxidant is provided. The phenolic antioxidant used herein is preferably a phenolic compound having in a molecule at least one structure of the following formula:



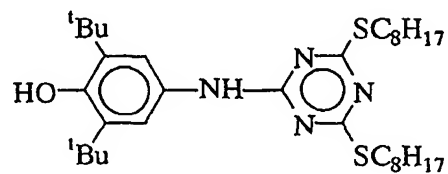
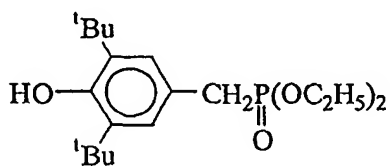
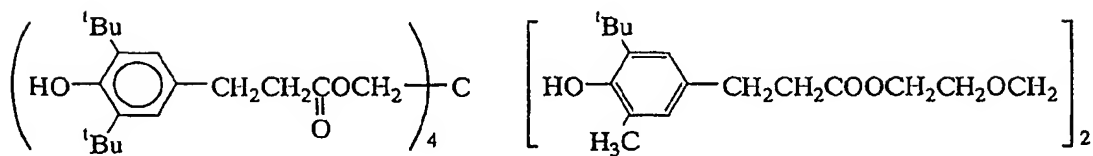
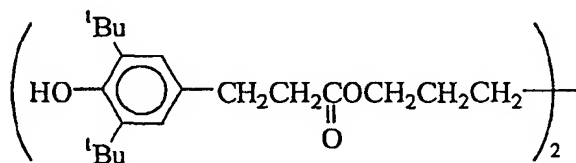
wherein R is a monovalent hydrocarbon group having 1 to 6 carbon atoms, typically alkyl group, most preferably tert-butyl.

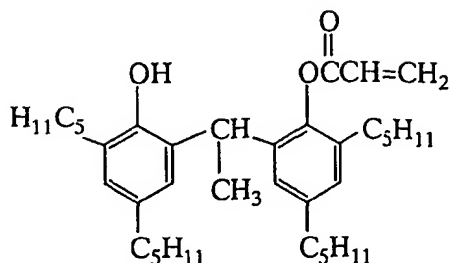
[0015] Illustrative examples of the phenolic antioxidant are shown below. Note that ^tBu is tert-butyl.





$$(m \geq 0, n \geq 1)$$





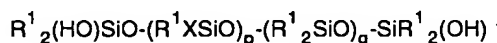
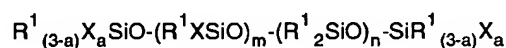
[0016] The phenolic antioxidant is preferably blended in an amount of at least 0.05wt%, especially at least 0.1wt% of the adhesive composition as a whole. The amount is preferably not more than 20wt%, more preferably up to 10wt%.

[0017] As used herein, the silicone pressure-sensitive adhesive composition may be selected from various compositions of well-known formulation and curing type, preferably silicone pressure-sensitive adhesive compositions of the addition reaction curing type.

[0018] Preferred silicone pressure-sensitive adhesive compositions contain the following components:

- (A) an alkenyl group-containing polydiorganosiloxane,
- (B) a polyorganosiloxane containing $R^1_3SiO_{0.5}$ units and SiO_2 units,
- (C) a SiH group-containing polyorganosiloxane (i.e., polyorganohydrogensiloxane),
- (D) a retarder,
- (E) a platinum catalyst, and
- (F) the phenolic antioxidant defined above.

[0019] They are described in detail. First, component (A) is an alkenyl group-containing polydiorganosiloxane, which is preferably represented by either of the formulae below.



Herein, R^1 is a monovalent hydrocarbon group free of aliphatic unsaturation, X is an alkenyl-containing organic group, a is an integer of 0 to 3, preferably 1, m is a number of at least 0, n is a number of at least 100, a and m are not 0 at the same time, p is a number of at least 1, and q is a number of at least 100.

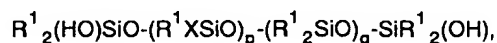
[0020] Preferred groups represented by R^1 are those of 1 to 10 carbon atoms, for example, alkyl groups such as methyl, ethyl, propyl and butyl, cycloalkyl groups such as cyclohexyl, aryl groups such as phenyl and tolyl, with methyl and phenyl being most preferred.

[0021] Preferred alkenyl-containing organic groups represented by X are those of 2 to 10 carbon atoms, for example, vinyl, allyl, hexenyl, octenyl, acryloylpropyl, acryloylmethyl, methacryloylpropyl, cyclohexenylethyl and vinyloxypropyl.

[0022] The polydiorganosiloxane may be oily or gum-like and have a viscosity of at least 50 mPa·s at 25°C, especially at least 100 mPa·s at 25°C. A mixture of two or more polydiorganosiloxanes is acceptable.

[0023] Component (B) is a polyorganosiloxane containing $R^1_3SiO_{0.5}$ units and SiO_2 units wherein R^1 is as defined above, and the molar ratio of $R^1_3SiO_{0.5}$ units/ SiO_2 units is 0.6-1.7:1. If the molar ratio of $R^1_3SiO_{0.5}$ units/ SiO_2 units is less than 0.6, adhesive strength and tack may be low. If the molar ratio is more than 1.7, adhesive strength and holding power may be low. The polyorganosiloxane may contain hydroxy groups, preferably in an amount of 0 to 4.0% by weight. A mixture of two or more polyorganosiloxanes is acceptable.

[0024] A simple blend of components (A) and (B) may be used. If component (A) contains one of the formula:

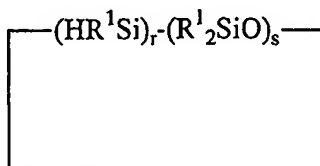
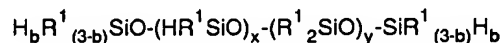


the condensation product of components (A) and (B) may be used. Such a product may be obtained by dissolving a mixture of components (A) and (B) in a solvent such as toluene, and effecting condensation reaction in the presence of a basic catalyst at room temperature or under reflux.

[0025] The blend ratio of component (A)/(B) is preferably from 20/80 to 80/20 by weight, especially from 30/70 to 70/30 by weight.

[0026] Component (C), which serves as a crosslinking agent, is an organohydrogenpolysiloxane having at least two, preferably at least three hydrogen atoms each attached to a silicon atom per molecule. It may be linear, branched or cyclic.

[0027] Preferred examples of component (C) are given below, but are not limited thereto.



Herein, R^1 is a hydrocarbon as defined previously, b is an integer of 0 to 3, and x and y are such integers that the organohydrogenpolysiloxane may have a viscosity of 1 to 5,000 mPa·s at 25°C. The letter r is an integer of at least 2, s is an integer of at least 0, $r+s$ is at least 3, preferably $r+s$ is from 3 to 8.

[0028] The organohydrogenpolysiloxanes should preferably have a viscosity of 1 to 5,000 mPa·s at 25°C and may be used in admixture of any.

[0029] Component (C) is used in an amount to provide 0.5 to 20 mol, especially 1 to 15 mol of SiH groups per mol of alkenyl groups in component (A). On this basis, less than 0.5 mol of SiH groups may lead to a lower crosslinking density which may entail a low holding power, whereas more than 20 mol of SiH groups may lead to losses of adhesive strength and tack.

[0030] Component (D) is a retarder, examples of which include 3-methyl-1-butyn-3-ol, 3-methyl-1-pentyn-3-ol, 3,5-dimethyl-1-hexyn-3-ol, 1-ethynylcyclohexanol, 3-methyl-3-trimethylsiloxy-1-butyne, 3-methyl-3-trimethylsiloxy-1-pentyne, 3,5-dimethyl-3-trimethylsiloxy-1-hexyne, 1-ethynyl-1-trimethylsiloxy-cyclohexane, bis(2,2-dimethyl-3-butyloxy)dimethylsilane, 1,3,5,7-tetramethyl-1,3,5,7-tetravinylcyclotetrasiloxane, and 1,1,3,3-tetramethyl-1,3-divinyl-disiloxane.

[0031] Component (D) is blended in an amount of 0 to 5.0 parts by weight, especially 0.05 to 2.0 parts by weight per 100 parts by weight of components (A) and (B) combined. More than 5.0 parts by weight of component (D) may hinder cure.

[0032] Component (E) is a platinum catalyst, examples of which include chloroplatinic acid, alcohol solutions of chloroplatinic acid, the reaction products of chloroplatinic acid with alcohols, the reaction products of chloroplatinic acid with olefins, and the reaction products of chloroplatinic acid with vinyl-containing siloxanes.

[0033] The platinum catalyst is added in an amount to give 1 to 5,000 ppm, especially 5 to 2,000 ppm of platinum based on the weight of components (A) and (B) combined. Less than 1 ppm of platinum may lead to under-cure, a low crosslinking density and a low holding power whereas more than 5,000 ppm of platinum may reduce the serviceable time of the solution.

[0034] To the addition curing type silicone pressure-sensitive adhesive composition described above, the phenolic antioxidant is added as component (F). The preferred amount of component (F) added is 0.1 to 10 parts by weight per 100 parts by weight of components (A) and (B) combined. Less than 0.1 part of component (F) may be insufficient to eliminate the adhesive residue whereas more than 10 parts may lead to a low holding power.

[0035] In addition to the above components, the silicone pressure-sensitive adhesive composition of the invention may further contain optional components. Included are nonreactive polyorganosiloxanes such as polydimethylsiloxane and polydimethyldiphenylsiloxane; solvents for lowering the viscosity upon application, for example, aromatic solvents such as toluene and xylene, aliphatic solvents such as hexane, octane and isoparaffin, ketone solvents such as methyl ethyl ketone and methyl isobutyl ketone, ester solvents such as ethyl acetate and isobutyl acetate, and ether solvents such as diisopropyl ether and 1,4-dioxane, and mixtures thereof; dyes and pigments.

[0036] The silicone pressure-sensitive adhesive composition formulated as above may be applied to a variety of supports and cured under predetermined conditions to form a pressure-sensitive adhesive layer.

[0037] Suitable supports include plastic films such as polyester, polytetrafluoroethylene, polyimide, polyphenylene sulfide, polyamide, polycarbonate, polystyrene, polypropylene, polyethylene, and polyvinyl chloride; metal foils such as aluminum foil and copper foil; papers such as Japanese paper, synthetic paper and polyethylene-laminated paper; fabrics; glass fibers; and composite supports having a plurality of layers of the foregoing materials laminated.

[0038] To improve the adhesion between the support and the adhesive layer, the support may be pretreated as by primer coating, corona treatment, etching treatment or plasma treatment.

[0039] Well-known application methods may be used to apply the composition to the support. Use may be made of, for example, a comma coater, lip coater, roll coater, die coater, knife coater, blade coater, rod coater, kiss-roll coater and gravure coater, as well as screen printing, dipping and casting techniques.

[0040] The buildup is adjusted such that the pressure-sensitive adhesive layer as cured has a thickness of 1 to 200 μm .

[0041] Curing conditions, but are not limited thereto, include 80 to 130°C and 30 seconds to 3 minutes in the case of addition reaction cure and 100 to 200°C and 30 seconds to 15 minutes in the case of peroxide cure.

[0042] A pressure-sensitive adhesive tape is prepared by directly applying the composition to the support as described above. Alternatively, the composition is applied to a release film or release paper (having a release coat thereon), cured thereto, and attached to the support whereupon the adhesive layer is transferred to the support to provide a pressure-sensitive adhesive tape.

[0043] The pressure-sensitive adhesive composition or tape of the invention is used in securing electric or electronic parts made of metals, especially copper or copper alloy when etching, plating or soldering treatment is carried out thereon, and as a masking tape to lead frames when semiconductor chips are secured, bonded, wire bonded or resin encapsulated during the manufacture of semiconductor devices.

[0044] Upon excursion to high temperatures of 150 to 250°C after the tape is attached to an adherend of metal, especially copper for holding or masking purposes, a preferred pressure-sensitive adhesive composition or tape of the invention can be smoothly peeled therefrom without leaving adhesive residues.

EXAMPLE

[0045] Examples of the invention are given below by way of illustration and not by way of limitation. All parts are by weight, Me is methyl, Vi is vinyl and ^tBu is tert-butyl. Test properties are reported as measurements by the test methods described below.

Adhesive residue

[0046] A silicone pressure-sensitive adhesive composition in solution form was applied to a polyimide film of 25 μm thick and 25 mm wide so as to give a thickness of 30 μm after curing and heat cured at 130°C for 1 minute, obtaining a pressure-sensitive adhesive tape. This adhesive tape was attached to a metal plate (polished copper plate or cold rolled steel strip). A rubber-lined roller having a weight of 2 kg was moved one stroke over the tape for bringing the tape in pressure contact with the metal plate. The assembly was held in a dryer at 200°C. After a predetermined time, the assembly was taken out and cooled down to room temperature whereupon the tape was peeled from the metal plate. It was observed whether or not the pressure-sensitive adhesive layer underwent cohesive failure so that the adhesive was left on the metal plate surface. Ratings are based on the following criterion.

- : no adhesive residue
- △: some adhesive residues
- X: adhesive residue on entire surface

Adhesive strength

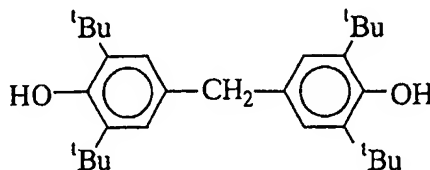
[0047] A pressure-sensitive adhesive tape was prepared as in the adhesive residue test. The tape was attached to a stainless steel plate. A rubber-lined roller having a weight of 2 kg was moved one stroke over the tape for bringing the tape in pressure contact with the metal plate. The assembly was held for about 20 hours at room temperature. Then using a tensile tester, a force (N/25 mm) required to peel the tape from the stainless steel plate at a speed of 300 mm/min and an angle of 180° was measured.

Holding power

[0048] A pressure-sensitive adhesive tape was prepared as in the adhesive residue test. The tape was attached to the lower side of a stainless steel plate over a bond area of 25×25 mm. A load having a weight of 1 kg was coupled to the lower side of the tape. The assembly was allowed to stand in the vertical state at 200°C for one hour, after which a slip distance (mm) of the tape was examined under a microscope.

Example 1

[0049] A silicone pressure-sensitive adhesive composition solution was prepared by mixing 100 parts of an addition reaction curing type silicone pressure-sensitive adhesive KR-3700 (Shin-Etsu Chemical Co., Ltd.), 50 parts of toluene, and 0.6 part of a phenolic antioxidant (A) of the formula shown below, and adding 0.5 part of a platinum catalyst CAT-PL-50T (Shin-Etsu Chemical Co., Ltd.) thereto, followed by further mixing.



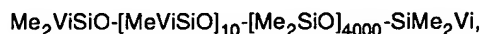
This silicone pressure-sensitive adhesive composition was examined for adhesive residue, adhesive strength and holding power, with the results shown in Table 1.

Comparative Example 1

[0050] A silicone pressure-sensitive adhesive composition solution was prepared as in Example 1, but omitting the phenolic antioxidant (A). This composition was examined for adhesive residue, adhesive strength and holding power, with the results shown in Table 1.

Comparative Example 2

[0051] A silicone pressure-sensitive adhesive composition having a siloxane content of about 60% was prepared by mixing 30 parts of an alkenyl-containing polydimethylsiloxane of the formula:



43 parts of a 70% toluene solution of a polysiloxane consisting of $\text{Me}_3\text{SiO}_{0.5}$ units and SiO_2 units in a ratio of 0.85/1, 27 parts of toluene, 0.38 part of a crosslinking agent of the formula:



and 0.1 part of ethynyl cyclohexanol. To 100 parts of the composition, 50 parts of toluene was added, followed by mixing. Then 0.5 part of a platinum catalyst CAT-PL-50T (Shin-Etsu Chemical Co., Ltd.) was added. Further mixing gave a silicone pressure-sensitive adhesive composition solution.

[0052] This composition was examined for adhesive residue, adhesive strength and holding power, with the results shown in Table 1.

Example 2

[0053] To the silicone pressure-sensitive adhesive composition solution of Comparative Example 2, 0.1 part of phenolic antioxidant (A) was added, followed by mixing.

[0054] This composition was examined for adhesive residue, adhesive strength and holding power, with the results shown in Table 1.

Example 3

[0055] To the silicone pressure-sensitive adhesive composition solution of Comparative Example 2, 5.0 parts of phenolic antioxidant (A) was added, followed by mixing.

[0056] This composition was examined for adhesive residue, adhesive strength and holding power, with the results shown in Table 1.

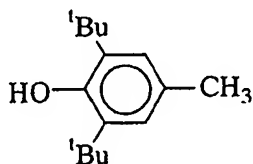
Example 4

[0057] To the silicone pressure-sensitive adhesive composition solution of Comparative Example 2, 15.0 part of phenolic antioxidant (A) was added, followed by mixing.

[0058] This composition was examined for adhesive residue, adhesive strength and holding power, with the results shown in Table 1.

Example 5

[0059] To the silicone pressure-sensitive adhesive composition solution of Comparative Example 2, 0.5 part of phenolic antioxidant (B) of the formula shown below was added, followed by mixing.



[0060] This composition was examined for adhesive residue, adhesive strength and holding power, with the results shown in Table 1.

Comparative Example 3

[0061] To the silicone pressure-sensitive adhesive composition solution of Comparative Example 2, 0.3 part of benzotriazole was added, followed by mixing.

[0062] This composition did not cure under heating conditions of 130°C and one minute.

Table 1

	Antioxidant (amount)	Metal plate	Adhesive residue										Adhesive strenght (N/ 25mm)	Holding power (mm)
			1	2	3	4	5	10	12	14	16	18h		
Example 1	A (0.5)	Copper	O	O	O	O	O	-	-	-	-	-	8.3	0.05
		Steel	-	-	-	-	-	O	O	O	O	O		
Comparative Example 1	nil	Copper	O	O	X	X	X	-	-	-	-	-	8.4	0.04
		Steel	-	-	-	-	-	O	Δ	X	X	X		
Comparative Example 2	nil	Copper	O	O	Δ	X	X	-	-	-	-	-	2.7	0.04
Example 2	A (0.1)	Copper	O	O	O	O	X	-	-	-	-	-	2.8	0.03
Example 3	A (5.0)	Copper	O	O	O	O	O	-	-	-	-	-	2.8	0.03
Example 4	A (15)	Copper	O	O	O	O	O	-	-	-	-	-	2.9	fell down
Example 5	B (0.5)	Copper	O	O	O	O	X	-	-	-	-	-	2.7	0.05
Comparative Example 3	benzotriazole (0.3)	-	adhesive did not cure											

[0063] Japanese Patent Application No. 2001-290863 is incorporated herein by reference.

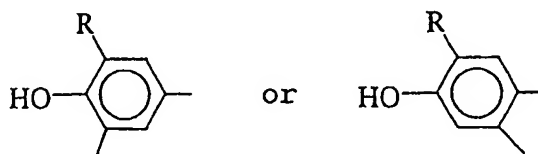
[0064] Although some preferred embodiments have been described, many modifications and variations may be made thereto in light of the above teachings. It is therefore to be understood that the invention may be practiced otherwise than as specifically described in the examples without departing from the scope of the general teachings herein.

Claims

1. A silicone pressure-sensitive adhesive composition comprising a phenolic antioxidant.

2. A silicone pressure-sensitive adhesive composition comprising

- (A) 20 to 80 parts by weight of an alkenyl group-containing polydiorganosiloxane,
- (B) 80 to 20 parts by weight of a polyorganosiloxane containing $R^1_3SiO_{0.5}$ units and SiO_2 units in a molar ratio between 0.6 and 1.7 wherein R^1 is a monovalent hydrocarbon group having 1 to 10 carbon atoms,
- (C) a SiH group-containing polyorganosiloxane in an amount to provide 0.5 to 20 mol of SiH groups per mol of alkenyl groups in component (A),
- (D) 0 to 5.0 parts by weight per 100 parts by weight of components (A) and (B) combined of a retarder,
- (E) a platinum catalyst in an amount to give 1 to 5,000 ppm of platinum based on the weight of components (A) and (B) combined, and
- (F) 0.1 to 10 parts by weight per 100 parts by weight of components (A) and (B) combined of a phenolic antioxidant in the form of a phenolic compound having in a molecule a structure of the following formula:



wherein R is a monovalent hydrocarbon group having 1 to 6 carbon atoms.

- 3. The silicone pressure-sensitive adhesive composition of claim 1 or 2 which is used in masking tape intended for electrical and electronic parts comprising copper or copper alloy.
- 4. A pressure-sensitive adhesive article comprising a cured layer of a silicone pressure-sensitive adhesive composition of claim 1 or 2 on at least one surface of a layer substrate.
- 5. An article according to claim 4 which is an adhesive tape, the substrate being a plastics film.
- 6. Use of an article according to claim 4 or 5 for masking e.g. copper or copper alloy components.



European Patent
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EUROPEAN SEARCH REPORT

Application Number
EP 02 25 6588

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Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int.Cl.7)
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The present search report has been drawn up for all claims			
Place of search MUNICH		Date of completion of the search 16 December 2002	Examiner Buestrich, R
<p>CATEGORY OF CITED DOCUMENTS</p> <p>X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document</p> <p>T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons & : member of the same patent family, corresponding document</p>			

EPO FORM 1503 (03.02) (P04C01)

**ANNEX TO THE EUROPEAN SEARCH REPORT
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This annex lists the patent family members relating to the patent documents cited in the above-mentioned European search report.
The members are as contained in the European Patent Office EDP file on
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